CSE460: VLSI Design

Lecture 5+6

CMOS Transistor Theory

Contents

- Introduction
- MOS Capacitor
- nMOS I-V Characteristics
- pMOS I-V Characteristics
- Gate and Diffusion Capacitance

Introduction

So far, we have treated transistors as ideal switches

An ON transistor passes a finite amount of current

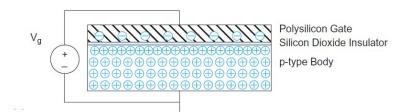
- Depends on terminal voltages
- Derive current-voltage (I-V) relationships

Transistor gate, source, drain all have capacitance

- $I = C (\Delta V / \Delta t) \rightarrow \Delta t = (C / I) \Delta V$
- Capacitance and current determine speed

MOS Capacitor

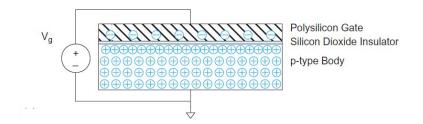
- The MOS transistor is a majority-carrier device
- Current in a conducting channel between the source and drain is controlled by a voltage applied to the gate
 - o nMOS majority carriers are electrons
 - pMOS majority carriers are holes
- First, let's examine an isolated MOS structure (of an nMOS) with a gate and body, but no source or drain



MOS Capacitor: Operating Modes

MOS Structure

- Top layer: Gate
 - A Good conductor, metal or polysilicon
- Middle layer: Oxide
 - Silicon dioxide, good insulator
- Bottom layer: Silicon (doped)
 - o nMOS: p-type, pMOS: n-type



Lets ground the body, connect a voltage source Vg between the gate and body

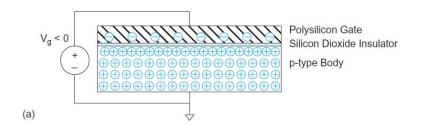
Value of *Vg* decides one of three <u>MOS operating modes</u>: (a) Accumulation, (b) Depletion & (c) Inversion

MOS Capacitor: Accumulation Mode

Case (a): **Vg < 0**

- a negative voltage is applied to the gate
- there is negative charge on the gate
- The mobile positively charged holes are attracted to the region beneath the gate

This is called the *accumulation* mode

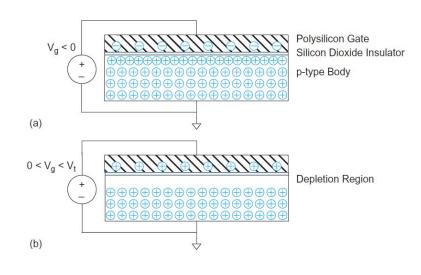


MOS Capacitor: Depletion Mode

Case (b): **0** < *Vg* < *Vt*

- a small positive voltage is applied to the gate
- resulting in some positive charge on the gate
- The holes in the body are repelled from the region directly beneath the gate, resulting in a *depletion* region forming below the gate

This is called the *depletion* mode

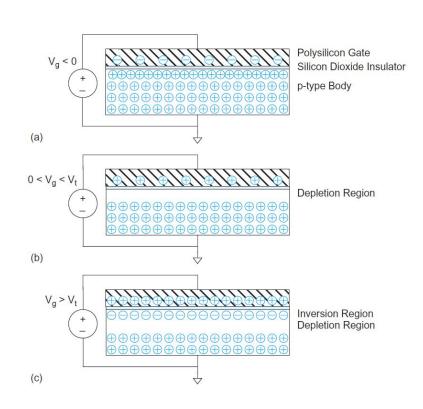


MOS Capacitor: Inversion Mode

Case (c): *Vg* > *Vt*

- a higher positive potential exceeding a critical threshold voltage Vt is applied
- more positive charge at the gate
- the holes are repelled further
- some free electrons in the body are attracted to the region beneath the gate
- this conductive layer of electrons in the p-type body is called the *inversion* layer

This is called the *inversion* mode



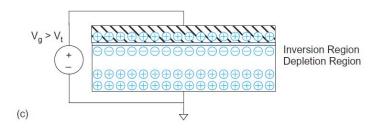
MOS Capacitor: Inversion Mode

Observation

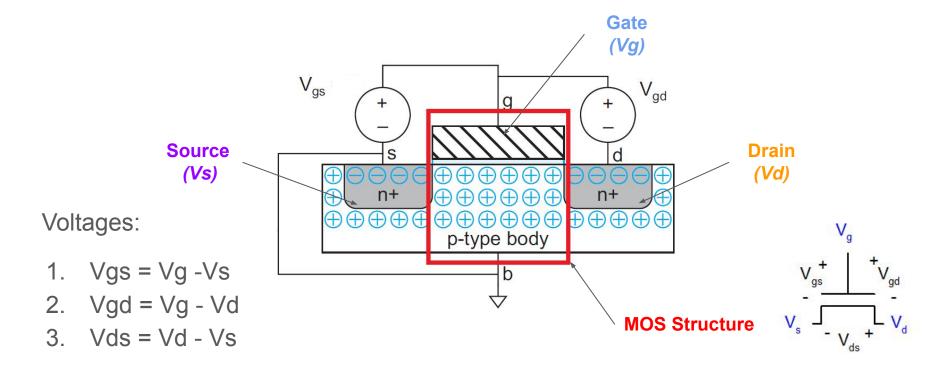
- To conduct current we need a channel between source and drain
- An inversion channel is formed only in the inversion mode when Vg > Vt
- Vt is called threshold voltage (Vt > 0)

Channel exists in **Inversion mode** (*Vg* > *Vt*)

No channel exists in **Accumulation or Depletion mode** (*Vg* < *Vt*)



nMOS Transistor



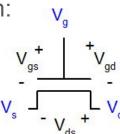
nMOS Transistor

The gate voltage *Vg* merely sets up the conduction path (inversion layer) in the body of the transistor underneath the gate, i.e. it is now ready to conduct current if a voltage is set up across the conducting path, between the source and drain.

The nMOS mode of operation hence depends on all three terminal voltages & the threshold voltage of the transistor: *Vg, Vd, Vs & Vt*

The source and drain are symmetric diffusion terminals. By convention:

- nMOS source is at lower voltage than drain while conducting
- Or, $Vd \ge Vs \Rightarrow Vd Vs \ge 0 \Rightarrow Vds \ge 0$
- nMOS body is grounded



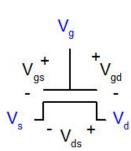
nMOS Transistor: Operating Regions

Depending on the terminal voltage and their differences, nMOS transistor could be operating in on of the following 3 regions:

- 1. **Cutoff** (No current flows)
- 2. **Linear** (Current flows & is *proportional* to the applied voltage)
- 3. **Saturation** (Current flows & is *independent* of the applied voltage)

We will develop the I-V characteristics for an nMOS transistor

Similar result can be obtained from analysis of a pMOS transistor.



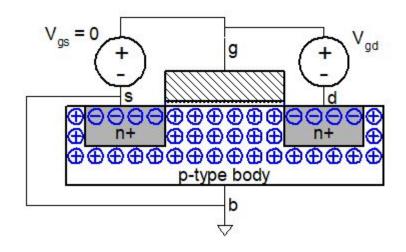
nMOS Transistor: Cutoff

Conditions:

- Vgs < Vt
- Vds (doesn't matter)

Results:

- No channel, hence no current
- $I_{ds} \approx 0$ independent of Vds



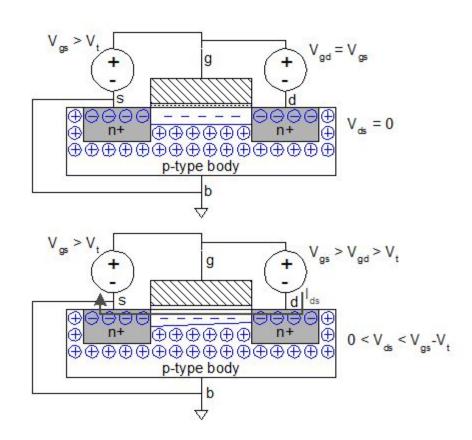
nMOS Transistor: Linear

Conditions:

- Vgs > Vt
- $0 \le Vds < Vgs Vt$

Results:

- Channel forms hence current flows
- I_{ds} increases with Vds
- Similar to a linear resistor



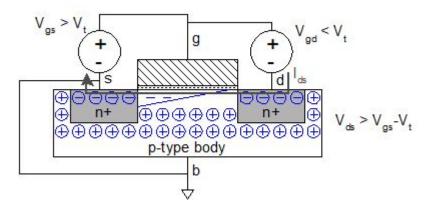
nMOS Transistor: Saturation

Conditions:

- Vgs ≥ Vt
- Vds ≥ Vgs Vt

Results:

- Channel forms, hence current flows
- \bullet $I_{ds} > 0$
- But channel is pinched off near the drain terminal, I_{ds} saturates
- Ids is independent of Vds
- Similar to a current source



nMOS Transistor Operating Regions: Summary

Vt: nMOS threshold voltage, Vt > 0 (nMOS device property)

Vgs: gate to source voltage, *Vgs* = *Vg* - *Vs*

Vds: drain to source voltage, *Vds* = *Vd* - *Vs*

	Vgs < Vt	Vgs ≥ Vt
0 < Vds < Vds(sat)	Cutoff	Linear
Vds ≥ Vds(sat)	Cutoff	Saturation

nMOS Transistor: I-V Summary

$$I_{ds} = \begin{cases} 0 & \text{if } V_{gs} < V_t \text{ (Cutoff)} \\ \beta(V_{gs} - V_t - \frac{V_{ds}}{2})V_{ds} & \text{if } V_{ds} < V_{ds(sat)} \text{ (Linear)} \\ \frac{\beta}{2}(V_{gs} - V_t)^2 & \text{if } V_{ds} \ge V_{ds(sat)} \text{ (Saturation)} \end{cases}$$

Where
$$\beta = \mu_n C_{ox} W/L \& V_{ds(sat)} = V_{gs} - V_t$$

pMOS Transistor Operating Regions: Summary

Vtp: pMOS threshold voltage, Vtp < 0 (pMOS device property)</pre>

Vsg: source to gate voltage, Vsg = Vs - Vg

Vsd: source to drain voltage, *Vsd* = *Vs - Vd*

	Vsg < Vtp	Vsg ≥ Vtp
0 < Vsd < Vsd(sat)	Cutoff	Linear
Vsd ≥ Vsd(sat)	Cutoff	Saturation

pMOS Transistor: I-V Summary

$$I_{sd} = \begin{cases} 0 & \text{if } V_{sg} < |V_{tp}| \text{ (Cutoff)} \\ \beta_p(V_{sg} - |V_{tp}| - \frac{V_{sd}}{2})V_{sd} & \text{if } V_{sd} < V_{sd(sat)} \text{ (Linear)} \\ \frac{\beta_p}{2}(V_{sg} - |V_{tp}|)^2 & \text{if } V_{sd} \ge V_{sd(sat)} \text{ (Saturation)} \end{cases}$$

Where
$$\beta_p = \mu_p C_{ox} W/L \& V_{sd(sat)} = V_{sq} - |V_{tp}|$$

MOSFET Capacitance

Any two conductors separated by an insulator have capacitance

Gate to channel capacitor is very important ($gate\ capacitance:\ C_g$)

Creates channel charge necessary for operation

Source and drain have capacitance to body (diffusion capacitance: C_{sb} , C_{db})

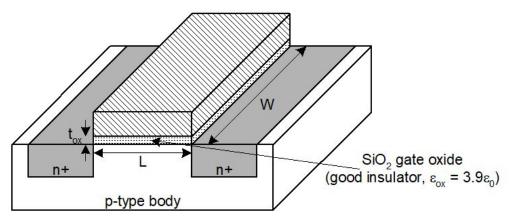
- Across reverse-biased diodes
- Called diffusion capacitance because it is associated with source/drain diffusion
- Remember that nMOS body is connected to ground and pMOS body is connected to supply (Vdd)

Gate Capacitance

 C_q = Gate capacitance

$$C_g = \varepsilon_{ox}WL/t_{ox} = C_{ox}WL = C_{permicron}W$$

C_{permicron} is typically about 2 fF/mm



Diffusion Capacitance

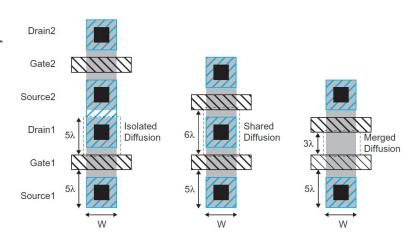
 C_{sh} = Source to body capacitance

 C_{db} = Drain to body capacitance

Undesirable, called parasitic capacitance

Capacitance depends on area and perimeter

- Use small diffusion nodes
- Comparable to C_q for contacted diff
- $\frac{1}{2}$ C_q for uncontacted
- Varies with process



Thank You!